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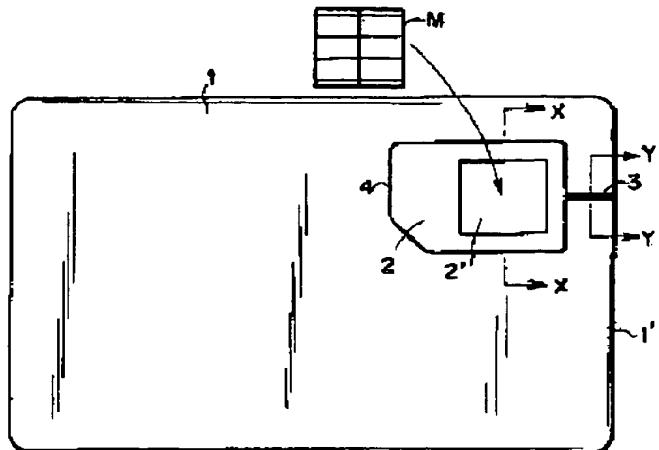
APPLICATION DATE : 13-01-98
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APPLICANT : MG:KK;

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TITLE : SUBSTRATE FOR IC CARD AND ITS
MANUFACTURING METHOD



ABSTRACT : PROBLEM TO BE SOLVED: To obtain an IC card capable of separating a part loaded with an IC module by a neat cutting face and securing the security of the IC module or the like until the card is issued to a user.

SOLUTION: The IC card consists of a body part 1 corresponding to standardized specification and a separating part 2 constituting a part of the body part 1 and including a surface loading an IC module M, a material having adhesion is selected as a material for forming at least either one of the body part 1 and the separating part 2 and an interface 4 between the body part 1 and the separating part 2 is incompletely fused so as to have adhesive strength capable of releasing a united body by the pressure of a finger.

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